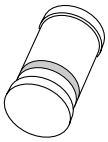


BAS32L

High-speed switching diode

Rev. 7 — 20 January 2011 **Product data sheet**

1. Product profile

1.1 General description

Single high-speed switching diode, fabricated in planar technology, and encapsulated in a small hermetically sealed glass SOD80C Surface-Mounted Device (SMD) package.

1.2 Features and benefits

- High switching speed: $t_{rr} \leq 4$ ns
- Reverse voltage: $V_R \leq 75$ V
- Repetitive peak reverse voltage: $V_{RRM} \leq 100$ V
- Repetitive peak forward current: $I_{FRM} \leq 450$ mA
- Small hermetically sealed glass SMD package

1.3 Applications

- High-speed switching
- Reverse polarity protection

1.4 Quick reference data

Table 1. Quick reference data

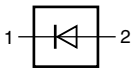
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
I_F	forward current		[1]	-	-	200	mA
I_{FRM}	repetitive peak forward current			-	-	450	mA
V_R	reverse voltage			-	-	75	V
V_F	forward voltage	I_F = 100 mA		-	-	1000	mV
t_{rr}	reverse recovery time		[2]	-	-	4	ns

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] When switched from I_F = 10 mA to I_R = 10 mA; R_L = 100 Ω; measured at I_R = 1 mA.

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	cathode [1]		 006aab040
2	anode		

[1] The marking band indicates the cathode.

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BAS32L	-	hermetically sealed glass surface-mounted package; 2 connectors	SOD80C

4. Marking

Table 4. Marking codes

Type number	Marking code
BAS32L	marking band

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{RRM}	repetitive peak reverse voltage			-	100	V
V_R	reverse voltage			-	75	V
I_F	forward current		[1]	-	200	mA
I_{FRM}	repetitive peak forward current			-	450	mA
I_{FSM}	non-repetitive peak forward current	square wave	[2]			
		t_p = 1 μs		-	4	A
		t_p = 1 ms		-	1	A
		t_p = 1 s		-	0.5	A

Table 5. Limiting values *...continued*

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
P_{tot}	total power dissipation	T_{amb} = 25 °C	[1]	-	500	mW
T_j	junction temperature			-	200	°C
T_{amb}	ambient temperature			−65	+200	°C
T_{stg}	storage temperature			−65	+200	°C

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] T_j = 25 °C prior to surge.

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	350	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	-	300	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

7. Characteristics

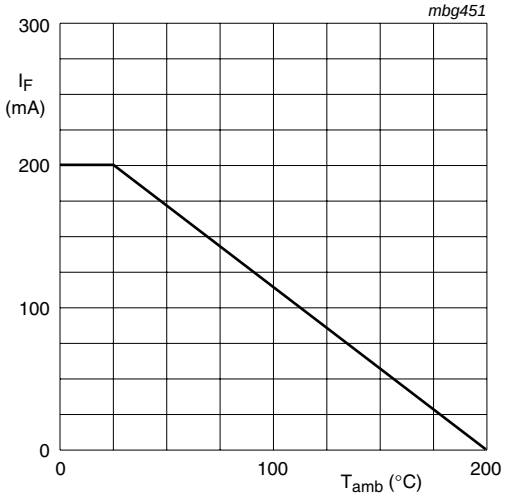
Table 7. Characteristics

T_{amb} = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_F	forward voltage	I_F = 5 mA		620	-	750	mV
		I_F = 100 mA		-	-	1000	mV
		I_F = 100 mA; T_j = 100 °C		-	-	930	mV
I_R	reverse current	V_R = 20 V		-	-	25	nA
		V_R = 75 V		-	-	5	µA
		V_R = 20 V; T_j = 150 °C		-	-	50	µA
		V_R = 75 V; T_j = 150 °C		-	-	100	µA
C_d	diode capacitance	V_R = 0 V; f = 1 MHz		-	-	2	pF
t_{rr}	reverse recovery time		[1]	-	-	4	ns
V_{FR}	forward recovery voltage		[2]	-	-	2.5	V

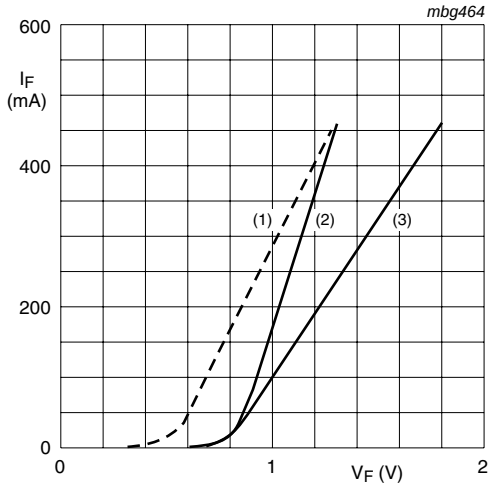
[1] When switched from I_F = 10 mA to I_R = 10 mA; R_L = 100 Ω; measured at I_R = 1 mA.

[2] When switched from I_F = 50 mA; t_r = 20 ns.



FR4 PCB, standard footprint

Fig 1. Forward current as a function of ambient temperature; derating curve

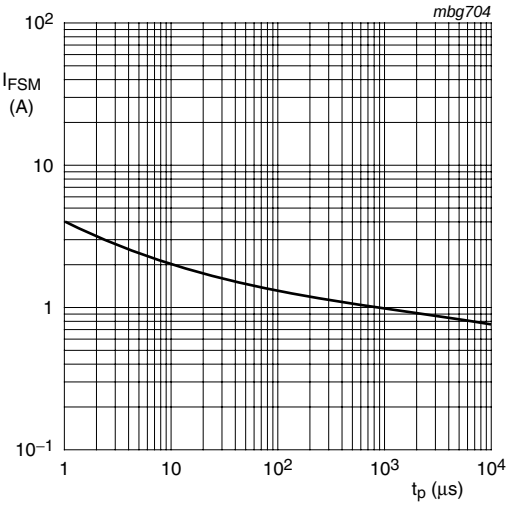


(1) T_j = 175 °C; typical values

(2) T_j = 25 °C; typical values

(3) T_j = 25 °C; maximum values

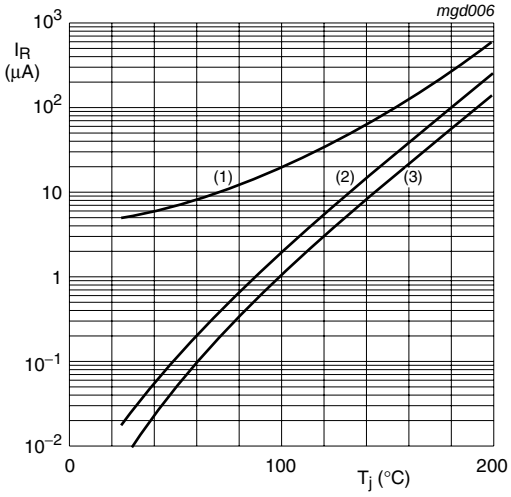
Fig 2. Forward current as a function of forward voltage



Based on square wave currents.

T_j = 25 °C prior to surge

Fig 3. Non-repetitive peak forward current as a function of pulse duration; maximum values

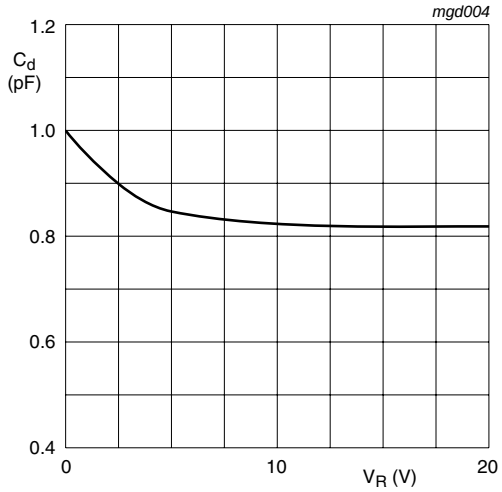


(1) V_R = 75 V; maximum values

(2) V_R = 75 V; typical values

(3) V_R = 20 V; typical values

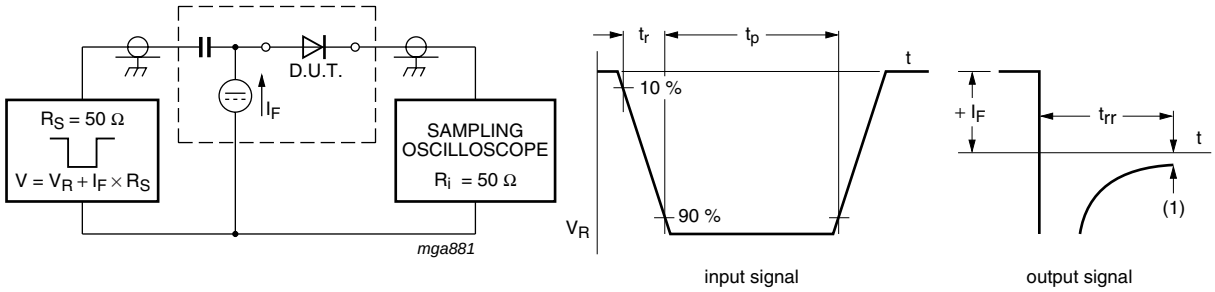
Fig 4. Reverse current as a function of junction temperature



f = 1 MHz; T_j = 25 °C

Fig 5. Diode capacitance as a function of reverse voltage; typical values

8. Test information

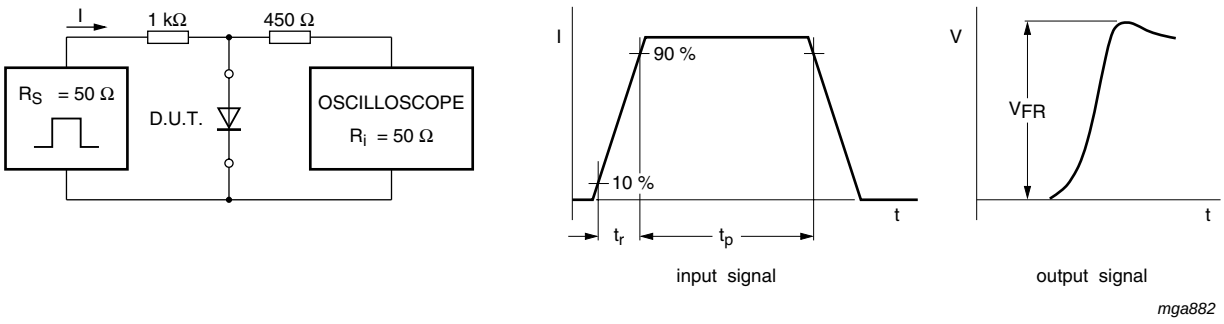


Input signal: Reverse pulse rise time t_r = 0.6 ns; reverse voltage pulse duration t_p = 100 ns; duty factor $\delta \leq 0.05$

Oscilloscope: Rise time t_r = 0.35 ns

(1) I_R = 1 mA

Fig 6. Reverse recovery time test circuit and waveforms



Input signal: Forward pulse rise time t_r = 20 ns; forward current pulse duration $t_p \geq 100$ ns; duty factor $\delta \leq 0.005$

Fig 7. Forward recovery voltage test circuit and waveforms

9. Package outline

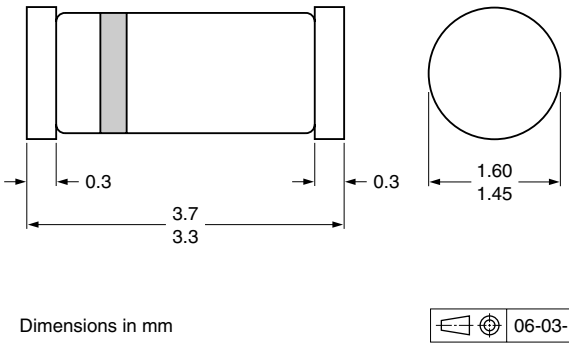


Fig 8. Package outline SOD80C

10. Packing information

Table 8. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.[1]

Type number	Package	Description	Packing quantity	
			2500	10000
BAS32L	SOD80C	4 mm pitch, 8 mm tape and reel	-115	-135

[1] For further information and the availability of packing methods, see Section 14.

11. Soldering

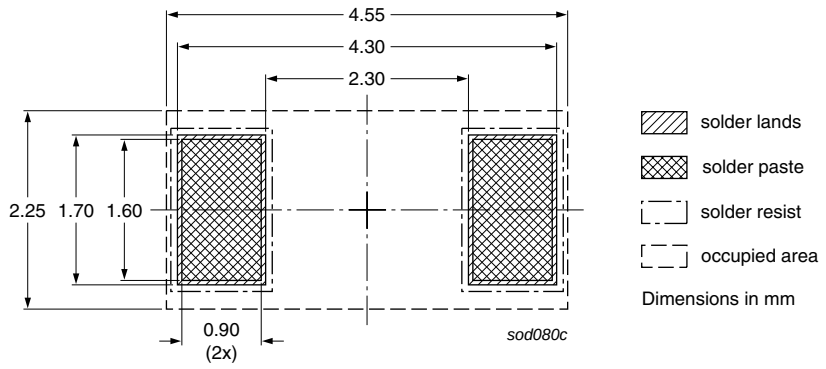


Fig 9. Reflow soldering footprint SOD80C

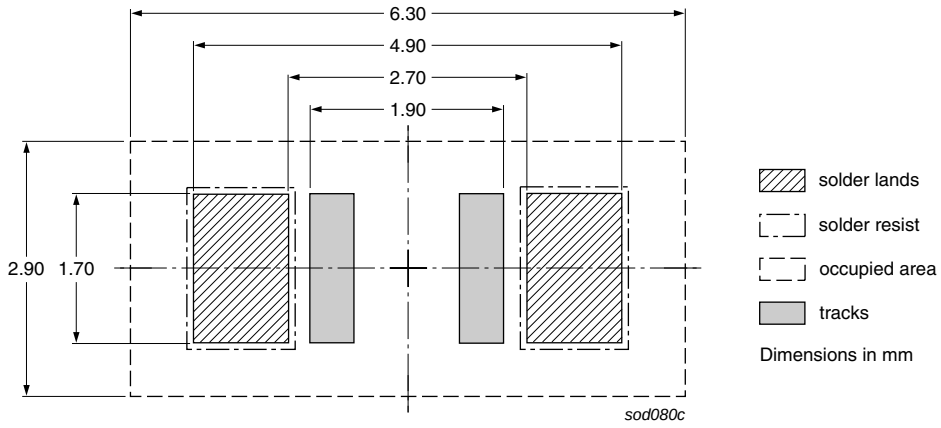


Fig 10. Wave soldering footprint SOD80C

12. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAS32L v.7	20110120	Product data sheet	-	BAS32L v.6
Modifications:	• Table 4 “Marking codes”: amended • Section 13 “Legal information”: updated			
BAS32L v.6	20081029	Product data sheet	-	BAS32L v.5
BAS32L v.5	20080103	Product data sheet	-	BAS32L v.4
BAS32L v.4	20050322	Product data sheet	-	BAS32L v.3
BAS32L v.3	20020123	Product specification	-	BAS32L v.2
BAS32L v.2	19960910	Product specification	-	BAS32L v.1
BAS32L v.1	19960423	Product specification	-	-

13. Legal information

13.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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